NOTICE OF REVISION (NOR) (See MIL-STD-480 for instructions)

This revision described below has been authorized for the document listed

DATE (YYMMDD)

Form Approved OMB No. 0704-0188

93-03-26

Public reporting burden for this collection is estimated to average 1 hour per response, including the time for reviewing instructions, searching existing data sources, gathering and maintaining the data needed, and completing and reviewing the collection of information. Send comments regarding this burden estimate or any other aspect of this collection of information, including suggestions for reducing this burden, to Washington Headquarters Services, Directorate for Information Operations and Reports, 1215 Jefferson Davis Highway, Suite 1204, Arlington, VA 22202-4302, and to the Office of Information and Regulatory Affairs, Office of Management and Budget, Washington, DC 20503.

1. ORIGINATOR NAME AND ADDRESS	2. CAGE CODE	3. NOR NO.
Defense Electronics Supply Center	67268	5962-R117-93
Dayton, Ohio 45444-5270	4. CAGE CODE	5. DOCUMENT NO.
	67268	5962-87749
6. TITLE OF DOCUMENT	7. REVISION LETTER	
MICROCIRCUIT, DIGITAL, ECL, TWO MODULUS PRESCALER,	A (Current)	B (New)
DIVIDE BY 10 AND 11, MONOLITHIC SILICON	8. ECP NO.	
	N/A	A

9. CONFIGURATION ITEM (OR SYSTEM) TO WHICH ECP APPLIES

ΑII

10. DESCRIPTION OF REVISION

Sheet 1: Revisions Itr column; add "B".

Revisions description column; add "Changes in accordance with

NOR 5962-R117-93".

Revisions date column; add "93-03-26". Revision level block; change from "A" to "B".

Rev status of sheets, for sheets 1 and 9; change from "A" to "B". For

sheets 15 and 16: add "B".

Sheet 9: Table I, toggle frequency, symbol column; change from "f $_{max \div 9}$ " to "f $_{max \div 11}$ ".

Revision level block; change from "A" to "B".

Sheet 15: Figure 4, test circuit; resistor connected to Q (pin 3); add " 100Ω ".

Revision level block; add "B".

Sheet 16: Figure 4, second waveform; change from "5 CYCLES" to "6 CYCLES" and

from "4 CYCLES" to "5 CYCLES".

Figure 4, waveforms for $t_{\mbox{\footnotesize SETUP}};$ change from "÷ 8" to "÷ 10".

Figure 4, waveforms for t_{RELEASE}; change from "÷ 9" to "÷ 11". Revision level block; add "B".

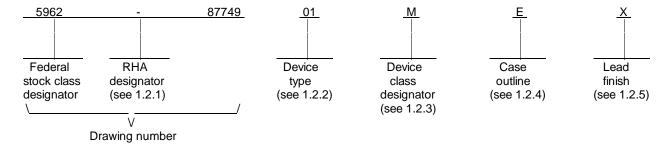
11. THIS SECTION FOR GOVERNMENT USE ONLY

a. CHECK ONE [X] EXISTING DOCUMENT SUPPLEMENTED BY THIS NOR MAY BE USED IN MANUFACTURE.	[] REVISED DOCUMENT MUST BE RECEIVED BEFORE MANUFACTURER MAY INCORPORATE THIS CHANGE.	[] CUSTODIAN OF MASTER DOCUMENT SHALL MAKE ABOVE REVISION AND FURNISH REVISED DOCUMENT TO:
b. ACTIVITY AUTHORIZED TO APPROVE CHANGE FOR GOVERNMENT DESC-ECC	SIGNATURE AND TITLE Monica L. Poelking Chief, Custom Microelectronics	DATE (YYMMDD) 93-03-26
12. ACTIVITY ACCOMPLISHING REVISION	REVISION COMPLETED (Signature)	DATE (YYMMDD)
DESC-ECC	Thanh V. Nguyen	93-03-26

REV											ONS	EVISI	R								
0.4 mA*. Table I, footnote Jf, delete in its entirety and replace as follows:	PPROVED		,	OA)	R-MO-E	ATE (Y	DA	4					N	IPTIO	ESCR	D					LTR
SHEET	a L. Poelking	nica L.	Moi		1-02	92-1			lows:) to	as foll 100Ω diagra	eplace ers and logic	and reamete amete o new	ntirety tic par nodify	in its e for sta re 3, n	delete -2.0 V . Figu	te <u>1</u> /, α 0Ω to ieters"	footno be 10 paran	able I, d shall CL AC	nA". T out loa ′ for E0	0.4 m "Outp 0.0 V	A
REV								7	_												
SHEET 15 16 17 18 19 20	++							+	<u> </u>												
REV STATUS OF SHEETS REV A A A A A A A A A A A A A A A A A A A	++							+													
SHEET 1 2 3 4 5 6 7 8 9 10 11 12 PMIC N/A PREPARED BY Phu H. Nguyen CHECKED BY Tim Noh THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DRAWING APPROVAL DATE SHEET 1 2 3 4 5 6 7 8 9 10 11 12 DEFENSE ELECTRONICS SUPPLY CENTE DAYTON, OHIO 45444 MICROCIRCUIT, DIGITAL, ECL, TWO MODUL PRESCALER, DIVIDE BY 10 AND 11, MONOL SILICON	++							+	-						20	19	18	17	16	15	SHEET
PMIC N/A PREPARED BY Phu H. Nguyen CHECKED BY Tim Noh THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DRAWING SHEET 1 2 3 4 5 6 7 8 9 10 11 12 DEFENSE ELECTRONICS SUPPLY CENTE DAYTON, OHIO 45444 MICROCIRCUIT, DIGITAL, ECL, TWO MODUL PRESCALER, DIVIDE BY 10 AND 11, MONOL SILICON DRAWING APPROVAL DATE	\	Α					Α	+	<u> </u>					Α			REV				
MILITARY DRAWING THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE Tim Noh APPROVED BY Monica L. Poelking MICROCIRCUIT, DIGITAL, ECL, TWO MODUL PRESCALER, DIVIDE BY 10 AND 11, MONOL SILICON	DEFENSE ELECTRONICS SUPPLY CENTER							3	2	1	guyen	PAREC u H. N	PREI Ph	 D	IZE	ARD					
	MICROCIRCUIT, DIGITAL, ECL, TWO MODULUS PRESCALER, DIVIDE BY 10 AND 11, MONOLITHIC SILICON							Tim Noh APPROVED BY					APPI Mo	MILITARY DRAWING THIS DRAWING IS AVAILABLE FOR USE BY ALL							
AMSC N/A REVISION LEVEL SIZE CAGE CODE 67268 5962-877	7749							DRAWING APPROVAL DATE 92-07-13													

1. SCOPE

- 1.1 <u>Scope</u>. This drawing forms a part of a one part one part number documentation system (see 6.6 herein). Two product assurance classes consisting of military high reliability (device classes B, Q, and M) and space application (device classes S and V), and a choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). Device class M microcircuits represent non-JAN class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices". When available, a choice of radiation hardness assurance (RHA) levels are reflected in the PIN.
 - 1.2 PIN. The PIN shall be as shown in the following example:



- 1.2.1 <u>Radiation hardness assurance (RHA) designator</u>. Device classes M, B, and S RHA marked devices shall meet the MIL-M-38510 specified RHA levels and shall be marked with the appropriate RHA designator. Device classes Q and V RHA marked devices shall meet the MIL-I-38535 specified RHA levels and shall be marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.
 - 1.2.2 <u>Device type(s)</u>. The device type(s) shall identify the circuit function as follows:

Device type	Generic number	<u>Circuit function</u>
01	12513	Two-modulus prescaler, an ECL to TTL translator, with divide by 10 and 11

1.2.3 <u>Device class designator</u>. The device class designator shall be a single letter identifying the product assurance level as follows:

Device class

Device requirements documentation

M Vendor self-certification to the requirements for non-JAN class B microcircuits in accordance with 1.2.1 of MIL-STD-883

B or S Certification and qualification to MIL-M-38510

Q or V Certification and qualification to MIL-I-38535

1.2.4 <u>Case outline(s)</u>. For device classes M, B, and S, case outline(s) shall meet the requirements in appendix C of MIL-M-38510 and as listed below. For device classes Q and V, case outline(s) shall meet the requirements of MIL-I-38535, appendix C of MIL-M-38510, and as listed below.

Outline letter Case outline

E D-2 (16-lead, .840" x .310" x .200"), dual-in-line package

1.2.5 <u>Lead finish</u>. The lead finish shall be as specified in MIL-M-38510 for classes M, B, and S or MIL-I-38535 for classes Q and V. Finish letter "X" shall not be marked on the microcircuit or its packaging. The "X" designation is for use in specifications when lead finishes A, B, and C are considered acceptable and interchangeable without preference.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-87749
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 2

1.3 Absolute maximum ratings. 1/ Storage temperature range (T_S)-65° C to 175° C Lead temperature (soldering,10 seconds) +300° C Junction temperature (T_J) +165° C Thermal resistance, junction-to-case (Θ_{JC}) ... See MIL-M-38510, appendix C 1.4 Recommended operating conditions. 1.5 Digital logic testing for device classes Q and V. Fault coverage measurement of manufacturing

2. APPLICABLE DOCUMENTS

2.1 Government specifications, standards, bulletin, and handbook. Unless otherwise specified, the following specifications, standards, bulletin, and handbook of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATIONS

MILITARY

MIL-M-38510

- Microcircuits, General Specification for.

MIL-I-38535

- Integrated Circuits, Manufacturing, General Specification for.

STANDARDS

MILITARY

MIL-STD-480

- Configuration Control-Engineering Changes, Deviations and Waivers.

MIL-STD-883

- Test Methods and Procedures for Microelectronics.

BULLETIN

MILITARY

MIL-BUL-103

- List of Standardized Military Drawings (SMD's).

HANDBOOK MILITARY

MIL-HDBK-780 - Standardized Military Drawings.

(Copies of the specifications, standards, bulletin, and handbook required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

Values will be added when they become available.

STANDARDIZED MILITARY DRAWING	SIZE A		5962-87749
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 3

Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements for device class M shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein. The individual item requirements for device classes B and S shall be in accordance with MIL-M-38510 and as specified herein. For device classes B and S, a full electrical characterization table for each device type shall be included in this SMD. The individual item requirements for device classes Q and V shall be in accordance with MIL-I-38535, the device manufacturer's Quality Management (QM) plan, and as specified herein.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 for device classes M, B, and S and MIL-I-38535 for device classes Q and V and herein.
 - 3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein.
 - 3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 1.
 - 3.2.3 Truth and state diagram. The truth and state diagram shall be as specified on figure 2.
 - 3.2.4 Logic diagram. The logic diagram shall be as specified on figure 3.
 - 3.2.5 Test circuit and switching waveforms. The test circuit and switching waveforms shall be as specified on figure 4.
 - 3.2.6 Radiation exposure circuit. The radiation exposure circuit shall be as specified when available.
- 3.3 <u>Electrical performance characteristics and postirradiation parameter limits</u>. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full case operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table IIA. The electrical tests for each subgroup are defined in table I.
- 3.5 <u>Marking</u>. The part shall be marked with the PIN listed in 1.2 herein. Marking for device class M shall be in accordance with MIL-STD-883 (see 3.1 herein). In addition, the manufacturer's PIN may also be marked as listed in MIL-BUL-103. Marking for device classes B and S shall be in accordance with MIL-M-38510. Marking for device classes Q and V shall be in accordance with MIL-I-38535.
- 3.5.1 <u>Certification/compliance mark</u>. The compliance mark for device class M shall be a "C" as required in MIL-STD-883 (see 3.1 herein). The certification mark for device classes B and S shall be a "J" or "JAN" as required in MIL-M-38510. The certification mark for device classes Q and V shall be a "QML" as required in MIL-I-38535.
- 3.6 <u>Certificate of compliance</u>. For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.7.3 herein). For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.7.2 herein). The certificate of compliance submitted to DESC-ECC prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device class M the requirements of MIL-STD-883 (see 3.1 herein), or for device classes Q and V, the requirements of MIL-I-38535 and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required for device class M in MIL-STD-883 (see 3.1 herein) or device classes B and S in MIL-M-38510 or for device classes Q and V in MIL-I-38535 shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 <u>Notification of change for device class M.</u> For device class M, notification to DESC-ECC of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change as defined in MIL-STD-480.
- 3.9 <u>Verification and review for device class M</u>. For device class M, DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
- 3.10 <u>Microcircuit group assignment for device classes M, B, and S</u>. Device classes M, B, and S devices covered by this drawing shall be in microcircuit group number 33 (see MIL-M-38510, appendix E).
 - 3.11 Serialization for device class S. All device class S devices shall be serialized in accordance with MIL-M-38510.

STANDARDIZED MILITARY DRAWING	SIZE A		5962-87749
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 4

TABLE I. <u>Electrical performance characteristics</u>.

Test	Symbol		-55° (Condition	125°C <u>1</u> /			Group A	Lin	nits	Unit
			unles	_{CC} = 5.00 V ss otherwise	±10% 3 specified			sub- groups	Min	Max	
Output voltage high	V _{OH1}	V _{EE} = 0.0 V V _{CC} = 5.0 V	E5 MTTL	E4 MTTL	E3 MECL	E2 MECL	E1 MECL	[
(prescaler)		$V_{CCO} = 5.0 \text{ V}$ See figure 2	0.5 V 2.4 V 0.5 V 0.5 V 0.5 V	0.5 V 0.5 V 2.4 V 0.5 V 0.5 V 0.5 V	3.11 V 3.11 V 3.11 V 4.22 V 3.11 V 3.11 V	3.11 V 3.11 V 3.11 V 3.11 V 4.22 V 3.11 V	3.11 V 3.11 V 3.11 V 3.11 V 3.11 V 4.22 V	1	4.03	4.22	V
			E5 MTTL	E4 MTTL	E3 MECL	E2 MECL	E1 MECL				
			0.5 V 2.4 V 0.5 V 0.5 V 0.5 V 0.5 V	0.5 V 0.5 V 2.4 V 0.5 V 0.5 V 0.5 V	3.14 V 3.14 V 3.14 V 4.37 V 3.14 V 3.14 V	3.14 V 3.14 V 3.14 V 3.14 V 4.37 V 3.14 V	3.14 V 3.14 V 3.14 V 3.14 V 3.14 V 4.37 V	2	4.135	4.37	
			E5 MTTL	E4 MTTL	E3 MECL	E3 MECL	E3 MECL				1]
			0.5 V 2.4 V 0.5 V 0.5 V 0.5 V 0.5 V	0.5 V 0.5 V 2.4 V 0.5 V 0.5 V 0.5 V	3.04 V 3.04 V 3.04 V 4.12 V 3.04 V 3.04 V	3.04 V 3.04 V 3.04 V 3.04 V 4.12 V 3.04 V	3.04 V 3.04 V 3.04 V 3.04 V 3.04 V 4.12 V	3	3.88	4.12	
Output voltage	V _{OL1}		E5 MTTL		E3 MECL		E1 MECL				
low (prescaler)			0.5 V 2.4 V 0.5 V 0.5 V 0.5 V 0.5 V	0.5 V 0.5 V 2.4 V 0.5 V 0.5 V 0.5 V	3.11 V 3.11 V 3.11 V 4.22 V 3.11 V 3.11 V	3.11 V 3.11 V 3.11 V 3.11 V 4.22 V 3.11 V	3.11 V 3.11 V 3.11 V 3.11 V 3.11 V 4.22 V	1	3.11	3.44	٧
			E5 MTTL	E4 MTTL	E3 MECL	E2 MECL	E1 MECL				
			0.5 V 2.4 V 0.5 V 0.5 V 0.5 V	0.5 V 0.5 V 2.4 V 0.5 V 0.5 V 0.5 V	3.14 V 3.14 V 3.14 V 4.37 V 3.14 V 3.14 V	3.14 V 3.14 V 3.14 V 3.14 V 4.37 V 3.14 V	3.14 V 3.14 V 3.14 V 3.14 V 3.14 V 4.37 V	2	3.14	3.515	
			E5 MTTL	E4 MTTL	E3 MECL	E3 MECL	E3 MECL				
			0.5 V 2.4 V 0.5 V 0.5 V 0.5 V 0.5 V	0.5 V 0.5 V 2.4 V 0.5 V 0.5 V 0.5 V	3.04 V 3.04 V 3.04 V 4.12 V 3.04 V 3.04 V	3.04 V 3.04 V 3.04 V 3.04 V 4.12 V 3.04 V	3.04 V 3.04 V 3.04 V 3.04 V 3.04 V 4.12 V	3	3.04	3.405	

STANDARDIZED MILITARY DRAWING	SIZE A		5962-87749
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 5

TABLE I. <u>Electrical performance characteristics</u> - Continued.

Test	Symbol		Conditions $-55^{\circ} \text{C} \leq \text{T}_{\text{C}} \leq +125^{\circ} \text{C} \qquad 1/$							nits	Unit
			V _{C0} unless	c = 5.00 V otherwise	±10% specified			sub- groups	Min	Max	
Output voltage high	V _{OH2}	$V_{EE} = 0.0 \text{ V}$ $V_{CC} = 5.0 \text{ V}$		V _{IHA} (+)	V _{IHB} (+)	V _{ILA} (-)	V _{ILB} (-)				
(translator)		MTTL output = -0.4	4 mA	3.895 V 4.000 V 3.745 V	4.22 V 4.37 V 4.12 V	3.525 V 3.600 V 3.500 V	3.11 V 3.14 V 3.04 V	1 2 3	2.70 3.00 2.40	4.50 4.50 4.50	V
Output voltage low	V _{OL2}	V _{EE} = 0.0 V V _{CC} = 5.0 V		V _{IHA} (-)	V _{IHB} (-)	V _{ILA} (+)	V _{ILB} (+)				
(translator)		MTTL output = 16	mA	3.895 V 4.000 V 3.745 V	4.22 V 4.37 V 4.12 V	3.525 V 3.600 V 3.500 V	3.11 V 3.14 V 3.04 V	1 2 3	0.10 0.10 0.10	0.80 0.66 1.00	
Output voltage high	V _{OHA}	V _{EE} = 0.0 V	E5 MTTL	E4 MTTL	E3 MECL	E2 MECL	E1 MECL				
(prescaler)		$V_{CC} = 5.0 \text{ V}$ $V_{CCO} = 5.0 \text{ V}$ See figure 2	0.8 V 0.5 V	0.5 V 0.8 V 0.5 V 0.5 V 0.5 V 0.5 V 2.0 V 0.5 V	3.14 V 3.14 V 3.60 V 3.14 V 3.14 V 3.14 V 4.00 V 3.14 V	3.11 V 3.11 V 3.11 V 3.525 V 3.11 V 3.11 V 3.11 V 3.895 V 3.11 V E2 MECL 3.14 V 3.14 V 3.60 V 3.14 V 3.14 V 3.14 V 3.14 V 3.14 V 3.14 V	3.14 V 3.14 V 3.14 V 3.14 V 3.60 V 3.14 V 3.14 V 3.14 V 3.14 V	2	4.115	4.50	V
			0.5 V E5 MTTL	0.5 V E4 MTTL	3.14 V E3 MECL	3.14 V E2 MECL	4.00 V E1 MECL				
			0.8 V 0.5 V 0.5 V 0.5 V 0.5 V 2.0 V 0.5 V 0.5 V 0.5 V	0.5 V 0.8 V 0.5 V 0.5 V 0.5 V 0.5 V 2.0 V 0.5 V 0.5 V	3.04 V 3.04 V 3.50 V 3.04 V 3.04 V 3.04 V 3.745 V 3.04 V 3.04 V	3.04 V 3.04 V 3.04 V 3.50 V 3.04 V 3.04 V 3.04 V 3.745 V 3.04 V	3.04 V 3.04 V 3.04 V 3.04 V 3.50 V 3.04 V 3.04 V 3.04 V 3.745 V	3	3.86	4.50	V

STANDARDIZED MILITARY DRAWING	SIZE A		5962-87749
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 6

TABLE I. <u>Electrical performance characteristics</u> - Continued.

Test	Symbol				Group	Liı	mits	Unit			
			$V_{\mathbf{C}}$	$6 \le T_C \le +12$ $0_C = 5.00 \text{ V}$ s otherwise	/ ±10%		ļ	A sub- groups	Min	Max	
Output voltage low (prescaler)	V _{OLA}	V _{EE} = 0.0 V V _{CC} = 5.0 V V _{CCO} = 5.0 V	0.8 V 0.5 V	0.5 V 0.8 V	E3 MECL 3.11 V 3.11 V	3.11 V 3.11 V	E1 MECL 3.11 V 3.11 V	1	3.11	3.46	V
		See figure 2	0.5 V 0.5 V 0.5 V 2.0 V	0.5 V 0.5 V 0.5 V 0.5 V	3.525 V 3.11 V 3.11 V 3.11 V	3.11 V 3.525 V 3.11 V 3.11 V	3.11 V 3.11 V 3.525 V 3.11 V				
			0.5 V 0.5 V 0.5 V 0.5 V	2.0 V 0.5 V 0.5 V 0.5 V	3.11 V 3.895 V 3.11 V 3.11 V	3.11 V 3.11 V 3.895 V 3.11 V	3.11 V 3.11 V 3.11 V 3.895 V				
			E5 MTTL 0.8 V	E4 MTTL 0.5 V	E3 MECL 3.14 V	3.14 V	E1 MECL 3.14 V	2	3 14	3.535	V
			0.5 V 0.5 V 0.5 V	0.8 V 0.5 V 0.5 V	3.14 V 3.60 V 3.14 V	3.14 V 3.14 V 3.60 V	3.14 V 3.14 V 3.14 V		3.14	3.333	
			0.5 V 2.0 V 0.5 V 0.5 V	0.5 V 0.5 V 2.0 V 0.5 V	3.14 V 3.14 V 3.14 V 4.00 V	3.14 V 3.14 V 3.14 V 3.14 V	3.60 V 3.14 V 3.14 V 3.14 V				
			0.5 V 0.5 V	0.5 V 0.5 V	3.14 V 3.14 V	4.00 V 3.14 V	3.14 V 4.00 V	<u> </u>			
			0.8 V 0.5 V 0.5 V 0.5 V 0.5 V 2.0 V	0.5 V 0.8 V 0.5 V 0.5 V 0.5 V 0.5 V	3.04 V 3.04 V 3.50 V 3.04 V 3.04 V 3.04 V	3.04 V 3.04 V 3.04 V 3.50 V 3.04 V 3.04 V	3.04 V 3.04 V 3.04 V 3.04 V 3.50 V 3.04 V	3	3.04	3.425	V
			0.5 V 0.5 V 0.5 V 0.5 V	2.0 V 0.5 V 0.5 V 0.5 V	3.04 V 3.745 V 3.04 V 3.04 V	3.04 V 3.04 V 3.745 V 3.04 V	3.04 V 3.04 V 3.04 V 3.745 V				
Reference bias supply voltage	V _{BB1}	$V_{EE} = 0.0 \text{ V} $ $V_{CC} = 5.0 \text{ V}$	V _{CCO} V _{BB} =	= 5.0 V (I _{OL} = 16 r	mA)			1	3.67	3.87	V
Output short circuit current (translator)	los	$V_{EE} = 0.0 \text{ V}$ MTTL $V_{CC} = 5.0$ MTTL Output = 0	V).5 V	V _{IHA} (+) 3.895 V 4.000 V 3.745 V	VIHB(+) 4.22 V 4.37 V 4.12 V	V _{ILA} (-) 3.525 V 3.600 V 3.500 V	V _{ILB} (-) 3.11 V 3.14 V 3.04 V	1, 2, 3	-65	-20	mA

STANDARDIZED MILITARY DRAWING	SIZE A		5962-87749
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL A	SHEET 7

TABLE I. <u>Electrical performance characteristics</u> - Continued.

Test	Symbol		Condition C ≤ T _C ≤ +		1/		Group A	Lir	nits	Unit
		V	$V_{CC} = 5.00 \text{ V} \pm 10\%$ unless otherwise specified				sub- groups	Min	Max	
Power supply current (prescaler)	I _{CC1}	$V_{CC} = 5.0 \text{ V}$ $V_{EE} = 5.0 \text{ V}$	= 0.0 V				1, 2, 3	-80		mA
Power supply current (translator)	I _{CC2}	$V_{EE} = 0.0 \text{ V}$ MTTL $V_{CC} = 5.0 \text{ V}$	V _{IHA} (-)	V _{IHB} (-)	V _{ILA} (+)	V _{ILB} (+)				
,		CC	3.895 V 4.00 V 3.745 V		3.525 V 3.600 V 3.500 V	3.11 V 3.14 V 3.04 V	1 2 3		5.2 5.2 5.2	mA
Input current high (MECL inputs	I _{INH1}	$V_{EE} = 0.0 \text{ V}$ E3 $V_{CC} = 5.0 \text{ V}$ E2	MECL = V _I MECL = V	HA/B	V_{IHA}	V_{IHB}				
prescaler)		$V_{CCO} = 5.0 \text{ V}$ E11	$V_{CCO} = 5.0 \text{ V}$		4.22 V 4.37 V 4.12 V	1 2 3		250 400 400	μΑ	
Input current high (- and + inputs	I _{INH2}	V _{EE} = 0.0 V MTTL V _{CC} = 5.0 V	V_{IHA}	V _{IHB}	V _{ILA}	V _{ILB}				
translator)		(-) = V _{IHA/B} (-) = V _{ILA/B} (+) = V _{IHA/B} (+) = V _{ILA/B}	3.895 V 4.00 V 3.745 V	4.22 V 4.37 V 4.12 V	3.525 V 3.600 V 3.500 V	3.11 V 3.14 V 3.04 V	1 2 3	2.0 2.0 1.7	6.0 6.4 6.0	mA
Input current high (+ input	I _{INH3}	$V_{EE} = 0.0 \text{ V}$ MTTL $V_{CC} = 5.0 \text{ V}$	V_{IHA}	V_{IHB}	V_{ILA}	V_{ILB}				
translator)		(-) = V _{IHA/B} (+) = V _{ILA/B}	3.895 V 4.00 V 3.745 V		3.525 V 3.600 V 3.500 V	3.11 V 3.14 V 3.04 V	1 2 3	1.0 1.0 0.7	3.0 3.6 3.0	mA
Input current high (MTTL inputs prescaler)	I _{INH4}	V _{EE} = 0.0 V E4 MTTL = 2.4 V V _{CC} = 5.0 V E5 MTTL = 2.4 V V _{CCO} = 5.0 V			1 2 3		100	μΑ		
Input current low (MECL inputs prescaler)	I _{INL1}	V _{EE} = 0.0 V E1 MECL = 0.0 V Clock = 0.0 V V _{CC} = 5.0 V E2 MECL = 0.0 V V _{CCO} = 5.0 V E3 MECL = 0.0 V			1 2 3	-10		μΑ		
Input current low (MTTL inputs prescaler)	I _{INL4}	I FF	TTL = 0.5 1TTL = 0.5				1 2 3	-1.6		mA
Functional test		See 4.4.1b					7, 8			

STANDARDIZED MILITARY DRAWING	SIZE A		5962-87749
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 8

 ${\sf TABLE\ I.\ } \underline{\sf Electrical\ performance\ characteristics} \text{-} \ {\sf Continued.}$

Test	Symbol	Conditions $-55^{\circ}\text{ C} \leq \text{T}_{\text{C}} \leq +125^{\circ}\text{ C}$ $\text{V}_{\text{CC}} = 5.00 \text{ V} \pm 10\%$ unless otherwise specif	<u>1</u> /	Group A subgroups	Lim Min	its Max	Unit
Propagation delay time (from input clock to output prescaler)	^t PLH1	$V_{EE} = -3.0 \text{ V}$ $V_{CC} = 2.0 \text{ V}$ $V_{CCO} = 2.0 \text{ V}$ MTTL $V_{CC} = 2.0 \text{ V}$ E1 MECL = V_{ILX}	V _{ILX} 0.215 V 0.260 V 0.165 V	9 10 11		8.1 9.4 8.1	ns
Propagation delay time (from input clock to invert output prescaler)	t _{PHL1}	E2 MECL = V _{ILX} E3 MECL = V _{ILX} E4 MTTL = -3.0 V E5 MTTL = -3.0 V		9 10 11		8.1 9.4 8.1	ns
Propagation delay time (from + input translator to MTTL output)	t _{PLH2}	See figure 4		9 10 11		8.1 9.4 8.1	ns
Propagation delay time (from + input translator to MTTL output)	t _{PHL2}			9 10 11		6.5 7.6 6.5	ns
Setup time MECL (inputs prescaler)	t _{setup1}			9, 10, 11	5.0		ns
Setup time MTTL (inputs prescaler)	t _{setup2}			9, 10, 11	5.0		ns
Release time MECL (inputs prescaler)	t _{release1}			9, 10, 11	5.0		ns
Release time MTTL (inputs prescaler)	t _{release2}			9, 10, 11	5.0		ns
Toggle frequency	f _{max÷9}	$V_{\rm EE}$ = -3.0 V $V_{\rm CC}$, $V_{\rm CCO}$, MTTTL $V_{\rm CC}$ = 2.0 E1 MECL, E2 MECL, E3 MECI E4 MTTL, E5 MTTL = -3.0 V) V L = -3.0	9, 10, 11	500		MHz

 $[\]underline{1}/$ Output load shall be 100Ω to -2.0 V for static parameters and 100Ω to 0.0 V for ECL AC parameters.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE A		5962-87749
	REVISION LEVEL A	SHEET 9

Terminal	Terminal symbol
number	Case outline
	Е
1	v _{cco}
2	Q
3	Q
4	(-)
5	(+)
6	MTTL V _{CC}
7	MTTL Output
8	V _{EE}
9	E5 MTTL
10	E4 MTTL
11	E3 MECL
12	E2 MECL
13	E1 MECL
14	V_{BB}
15	Clock
16	V _{CC}

FIGURE 1. Terminal connections.

STANDARDIZED MILITARY DRAWING	SIZE A		5962-87749
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 10

		Q ₁	02	Q 3	04	ENABLE	=	1
	-	1	1	1	1			
		0	1	1	1			
		0	0	1	1			
		0	0	0	1			
		1	0	0	1			
		1	1	0	1			
		0	1	1	0			
		0	0	1	0			
		0	0	0	0			
		1	0	0	0			
		1	1	0	0			
`								

ENABLE = 0

NOTE: The state of the enable is important only for the positive clock transition when the counter is the state 1100.

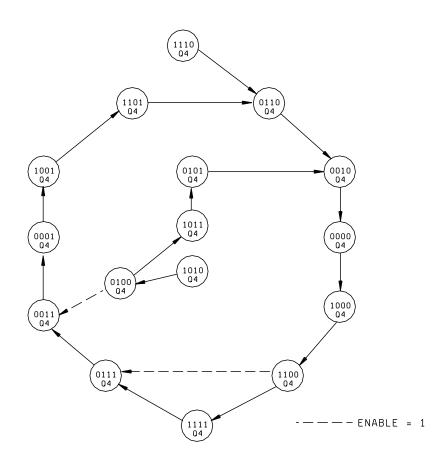


FIGURE 2. Truth and state diagram.

STANDARDIZED MILITARY DRAWING	SIZE A		5962-87749
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 11

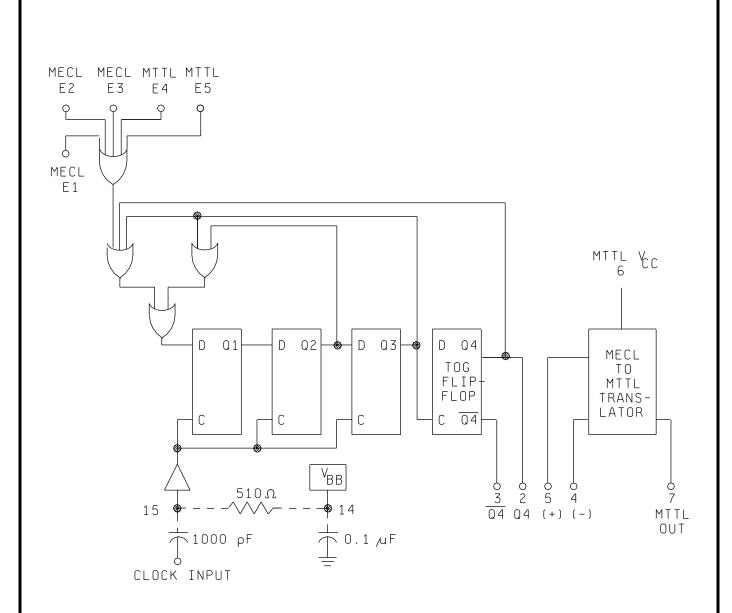
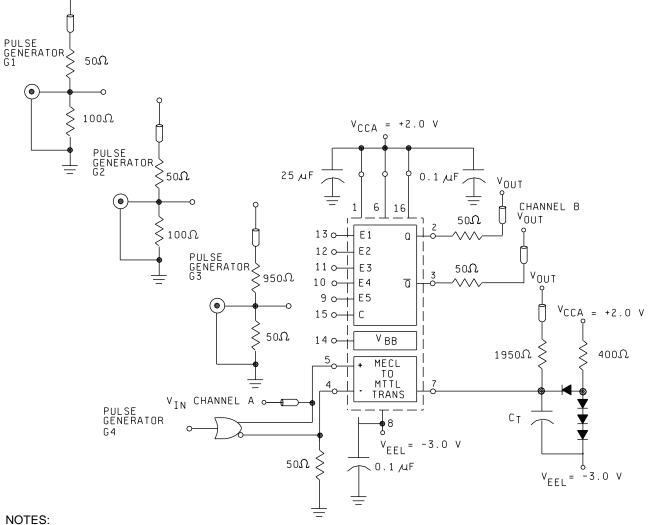


FIGURE 3. Logic diagram.

STANDARDIZED MILITARY DRAWING	SIZE A		5962-87749
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL A	SHEET 12

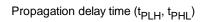
Propagation delay time (t_{PLH}, t_{PHL})



- 1. All resistors are ±1.0 percent.
- 2. All input and output cables to the scope are equal lengths of 50Ω coaxial cable.
- 3. The 1950Ω resistor at pin 7 and the scope termination impedance constitute a 40:1 attenuator probe.
- 4. All unused outputs must be terminated with 100Ω resistances to ground.
- 5. Pulse generators 1, 2, and 4 have the following characteristics:
 - a. PRF = 10 MHz.
 - b. PW = 50% duty cycle.
 - c. $t_r = t_f = 2.0 \text{ ns } \pm 0.2 \text{ ns.}$
- 6. Pulse generator 3 has the following characteristics:
 - a. PRF = 2 MHz.
 - b. PW = 50% duty cycle.
- c. $t_r = t_f = 5.0$ ns ± 0.5 ns. 7. $C_T = 15$ pF (including stray capacitance).

FIGURE 4. Test circuits and switching waveforms.

STANDARDIZED MILITARY DRAWING	SIZE A		5962-87749
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 13



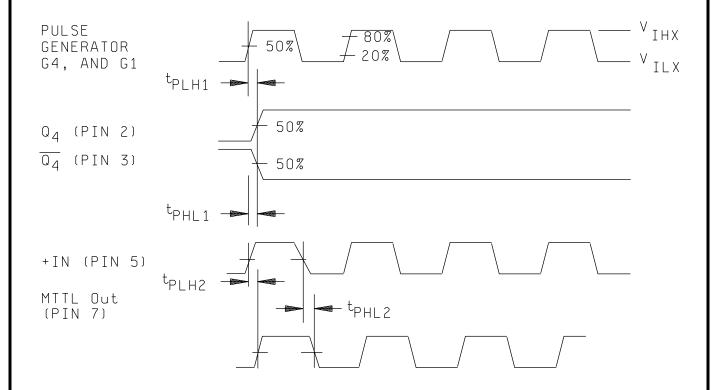


FIGURE 4. Test circuits and switching waveforms - Continued.

STANDARDIZED MILITARY DRAWING	SIZE A		5962-87749
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 14

Setup and release time (t_{setup} , $t_{release}$)

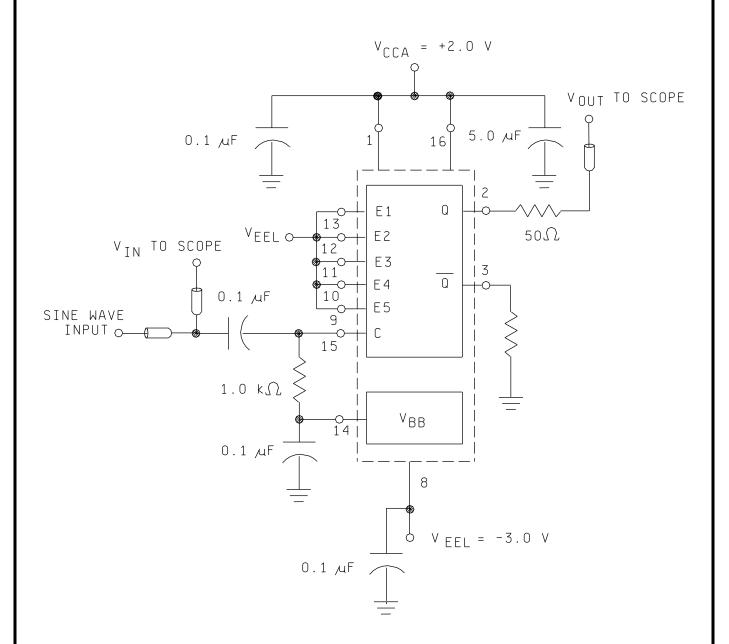


FIGURE 4. <u>Test circuits and switching waveforms</u> - Continued.

STANDARDIZED MILITARY DRAWING	SIZE A		5962-87749
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 15

Setup and release time (t_{setup} , $t_{release}$). CLOCK INPUT 800 mV 850 mV TYP 5 CYCLES 4 CYCLES PULSE GENERATOR 1 V_{ILX} t_{SETUP 1} V_{IHX} PULSE GENERATOR 2 $\mathsf{v}_{\mathsf{ILX}}$ tSETUP 2 0 V PULSE GENERATOR 3 v_{ILX} Q(pin 2) V_{OUT} VIHX PULSE

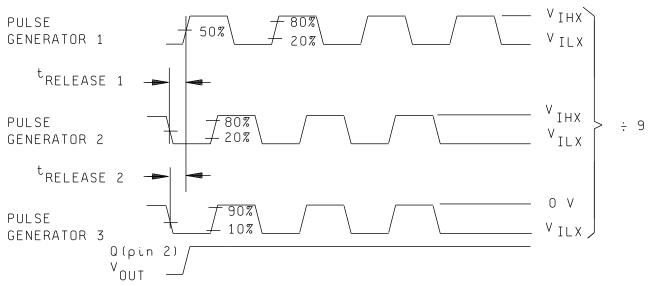


FIGURE 4. Test circuits and switching waveforms - Continued.

STANDARDIZED MILITARY DRAWING	SIZE A		5962-87749
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 16

4. QUALITY ASSURANCE PROVISIONS

- 4.1 <u>Sampling and inspection</u>. For device class M, sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein). For device classes B and S, sampling and inspection procedures shall be in accordance with MIL-M-38510 and method 5005 of MIL-STD-883, except as modified herein. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-I-38535 and the device manufacturer's QM plan.
- 4.2 <u>Screening</u>. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. For device classes B and S, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to qualification and quality conformance inspection. For device classes Q and V, screening shall be in accordance with MIL-I-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection.
 - 4.2.1 Additional criteria for device classes M, B, and S.
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. For device class M, the test circuit shall be submitted to DESC-ECC for review with the certificate of compliance. For device classes B and S, the test circuit shall be submitted to the qualifying activity.
 - (2) $T_{\Delta} = +125^{\circ} \text{ C}$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table IIA herein.
 - 4.2.2 Additional criteria for device classes Q and V.
 - a. The burn-in test duration, test condition and test temperature or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-I-38535. The burn-in test circuit shall be submitted to DESC-ECC with the certificate of compliance and shall be under the control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-I-38535.
 - b. Interim and final electrical test parameters shall be as specified in table IIA herein.
 - Additional screening for device class V beyond the requirements of device class Q shall be as specified in appendix B of MIL-I-38535 and as detailed in table IIB herein.
 - 4.3 Qualification inspection.
- 4.3.1 Qualification inspection for device classes B and S. Qualification inspection for device classes B and S shall be in accordance with MIL-M-38510. Inspections to be performed shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.5).
- 4.3.2 <u>Qualification inspection for device classes Q and V</u>. Qualification inspection for device classes Q and V shall be in accordance with MIL-I-38535. Inspections to be performed shall be those specified in MIL-I-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.5).
- 4.4 <u>Conformance inspection</u>. Quality conformance inspection for device class M shall be in accordance with MIL-STD-883 (see 3.1 herein) and as specified herein. Quality conformance inspection for device classes B and S shall be in accordance with MIL-M-38510 and as specified herein. Inspections to be performed for device classes M, B, and S shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.5). Technology conformance inspection for classes Q and V shall be in accordance with MIL-I-38535 including groups A, B, C, D, and E inspections and as specified herein except where option 2 of MIL-I-38535 permits alternate in-line control testing.

STANDARDIZED MILITARY DRAWING	SIZE A		5962-87749
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 17

TABLE IIA. Electrical test requirements.

Test requirements	Subgroups (per method 5005, table I)				roups 535, table III)
	Device class M	Device class B	Device class S	Device class Q	Device class V
Interim electrical parameters (see 4.2)	1	1	1	1	1
Final electrical parameters (see 4.2)	1, 2, 3, 7, 8, 9 <u>1</u> /	1, 2, 3, 7, 8, 9 <u>2</u> /	1, 2, 3, 7, 8, 9, 10, 11 <u>2</u> /	1, 2, 3, 7, 8, 9, 10, 11 <u>1</u> /	1, 2, 3, 7, 8, 9, 10, 11 <u>1</u> /
Group A test requirements (see 4.4)	1, 2, 3, 7, 8, 9, 10, 11	1, 2, 3, 7, 8, 9, 10, 11	1, 2, 3, 7, 8, 9, 10, 11	1, 2, 3, 7, 8, 9, 10, 11	1, 2, 3, 7, 8, 9, 10, 11
Group B end-point electrical parameters (see 4.4)			1, 2, 3		
Group C end-point electrical parameters (see 4.4)	1, 2, 3	1, 2, 3		1, 2, 3	1, 2, 3
Group D end-point electrical parameters (see 4.4)	1, 2, 3	1, 2, 3	1, 2, 3	1, 2, 3	1, 2, 3
Group E end-point electrical parameters (see 4.4)	1, 7, 9	1, 7, 9	1, 7, 9	1, 7, 9	1, 7, 9

- 1/ PDA applies to subgroup 1.
- 2/ PDA applies to subgroups 1 and 7.

4.4.1 Group A inspection.

- a. Tests shall be as specified in table IIA herein.
- b. For device class M, subgroups 7 and 8 tests shall be sufficient to verify the functionality of the device. For device classes B and S, subgroups 7 and 8 tests shall be sufficient to verify the functionality of the device as approved by the qualifying activity. For device classes Q and V, subgroups 7 and 8 shall include verifying the functionality of the device; these tests shall have been fault graded in accordance with MIL-STD-883, test method 5012 (see 1.5 herein).
- 4.4.2 <u>Group B inspection</u>. The group B inspection end-point electrical parameters shall be as specified in table IIA herein.
- 4.4.3 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table IIA herein.
- 4.4.3.1 Additional criteria for device classes M, B, and S. Steady-state life test conditions, method 1005 of MIL-STD-883:
 - a. Test condition A, B, C or D. For device class M, the test circuit shall be submitted to DESC-ECC for review with the certificate of compliance. For device classes B and S, the test circuit shall be submitted to the qualifying activity.
 - b. $T_A = +125^{\circ}C$, minimum.
 - c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
- 4.4.3.2 <u>Additional criteria for device classes Q and V.</u> The steady-state life test duration, test condition and test temperature or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-I-38535. The steady-state life test circuit shall be submitted to DESC-ECC with the certificate of compliance and shall be under the control of the device manufacturer's TRB in accordance with MIL-I-38535.

STANDARDIZED MILITARY DRAWING	SIZE A		5962-87749
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL A	SHEET 18

TABLE IIB. Additional screening for device class V.

Test	MIL-STD-883, test method	Lot requirement
Particle impact noise detection	2020	100%
Internal visual	2010, condition A or approved alternate	100%
Nondestructive bond pull	2023 or approved alternate	100%
Reverse bias burn-in	1015	100%
Burn-in	1015, total of 240 hours at +125° C	100%
Radiographic	2012	100%

- 4.4.4 <u>Group D inspection</u>. The group D inspection end-point electrical parameters shall be as specified in table IIA herein.
- 4.4.5 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein). RHA levels for device classes B, S, Q, and V shall be M, D, R, and H and for device class M shall be M and D. RHA quality conformance inspection sample tests shall be performed at the RHA level specified in the acquisition document.
 - a. RHA tests for device classes B and S for levels M, D, R, and H or for device class M for levels M and D shall be performed through each level to determine at what levels the devices meet the RHA requirements. These RHA tests shall be performed for initial qualification and after design or process changes which may affect the RHA performance of the device.
 - b. End-point electrical parameters shall be as specified in table IIA herein.
 - c. Prior to total dose irradiation, each selected sample shall be assembled in its qualified package. It shall pass the specified group A electrical parameters in table I for subgroups specified in table IIA herein.
 - d. For device classes M, B, and S, the devices shall be subjected to radiation hardness assured tests as specified in MIL-M-38510 for RHA level being tested, and meet the postirradiation end-point electrical parameter limits as defined in table I at T_A = +25° C ±5 percent, after exposure.
 - e. Prior to and during total dose irradiation testing, the devices shall be biased to establish a worst case condition as specified in the radiation exposure circuit.
 - f. For device classes M, B, and S, subgroups 1 and 2 in table V, method 5005 of MIL-STD-883 shall be tested as appropriate for device construction.
 - g. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.

5. PACKAGING

5.1 <u>Packaging requirements</u>. The requirements for packaging shall be in accordance with MIL-M-38510 for device classes M, B, and S and MIL-I-38535 for device classes Q and V.

STANDARDIZED MILITARY DRAWING	SIZE A		5962-87749
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 19

6. NOTES

- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.1.1 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
 - 6.1.2 Substitutability. Device classes B and Q devices will replace device class M devices.
- 6.2 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-481 using DD Form 1693, Engineering Change Proposal (Short Form).
- 6.3 Record of users. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and which SMD's are applicable to that system. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DESC-ECC, telephone (513) 296-8525.
- 6.4 <u>Comments</u>. Comments on this drawing should be directed to DESC-ECC, Dayton, Ohio 45444, or telephone (513) 296-8525.
- 6.5 One part one part number system. The one part one part number system described below has been developed to allow for transitions between identical generic devices covered by the four major microcircuit requirements documents (MIL-M-38510, MIL-H-38534, MIL-I-38535, and 1.2.1 of MIL-STD-883) without the necessity for the generation of unique PIN's. The four military requirements documents represent different class levels, and previously when a device manufacturer upgraded military product from one class level to another, the benefits of the upgraded product were unavailable to the Original Equipment Manufacturer (OEM), that was contractually locked into the original unique PIN. By establishing a one part number system covering all four documents, the OEM can acquire to the highest class level available for a given generic device to meet system needs without modifying the original contract parts selection criteria.

Military documentation format	Example PIN under new system	Manufacturing source listing	Document <u>listing</u>
New MIL-M-38510 Military Detail Specifications (in the SMD format)	5962-XXXXXZZ(B or S)YY	QPL-38510 (Part 1 or 2)	MIL-BUL-103
New MIL-H-38534 Standardized Military Drawings	5962-XXXXXZZ(H or K)YY	QML-38534	MIL-BUL-103
New MIL-I-38535 Standardized Military Drawings	5962-XXXXXZZ(Q or V)YY	QML-38535	MIL-BUL-103
New 1.2.1 of MIL-STD-883 Standardized Military Drawings	5962-XXXXXZZ(M)YY	MIL-BUL-103	MIL-BUL-103

- 6.6 <u>Sources of supply</u>.
- 6.6.1 Sources of supply for device classes B and S. Sources of supply for device classes B and S are listed in QPL-38510.
- 6.6.2 <u>Sources of supply for device classes Q and V</u>. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DESC-ECC and have agreed to this drawing.
- 6.6.3 <u>Approved sources of supply for device class M.</u> Approved sources of supply for class M are listed in MIL-BUL-103. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-ECC.

STANDARDIZED MILITARY DRAWING	SIZE A		5962-87749
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 20

STANDARDIZED MILITARY DRAWING SOURCE APPROVAL BULLETIN

DATE: 92-11-02

Approved sources of supply for SMD 5962-87749 are listed below for immediate acquisition only and shall be added to MIL-BUL-103 during the next revision. MIL-BUL-103 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DESC-ECC. This bulletin is superseded by the next dated revision of MIL-BUL-103.

Standardized	Vendor	Vendor
military drawing	CAGE	similar
PIN	number	PIN <u>1</u> /
5962-8774901MEX	04713	12513/BEAJC

1/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

Vendor name and address

04713

Motorola Incorporated 5005 E McDowell Road Phoenix, AZ 85008

Point of contact: 2100 E Elliot Road Tempe, AZ 85248

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in this information bulletin.